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(12) **United States Design Patent** (10) **Patent No.:** **US D776,071 S**
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(54) **POWER SEMICONDUCTOR MODULE**

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(52) **U.S. Cl.**
USPC **D13/182**

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361/775, 783, 820; 174/250, 253; 438/15,
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See application file for complete search history.

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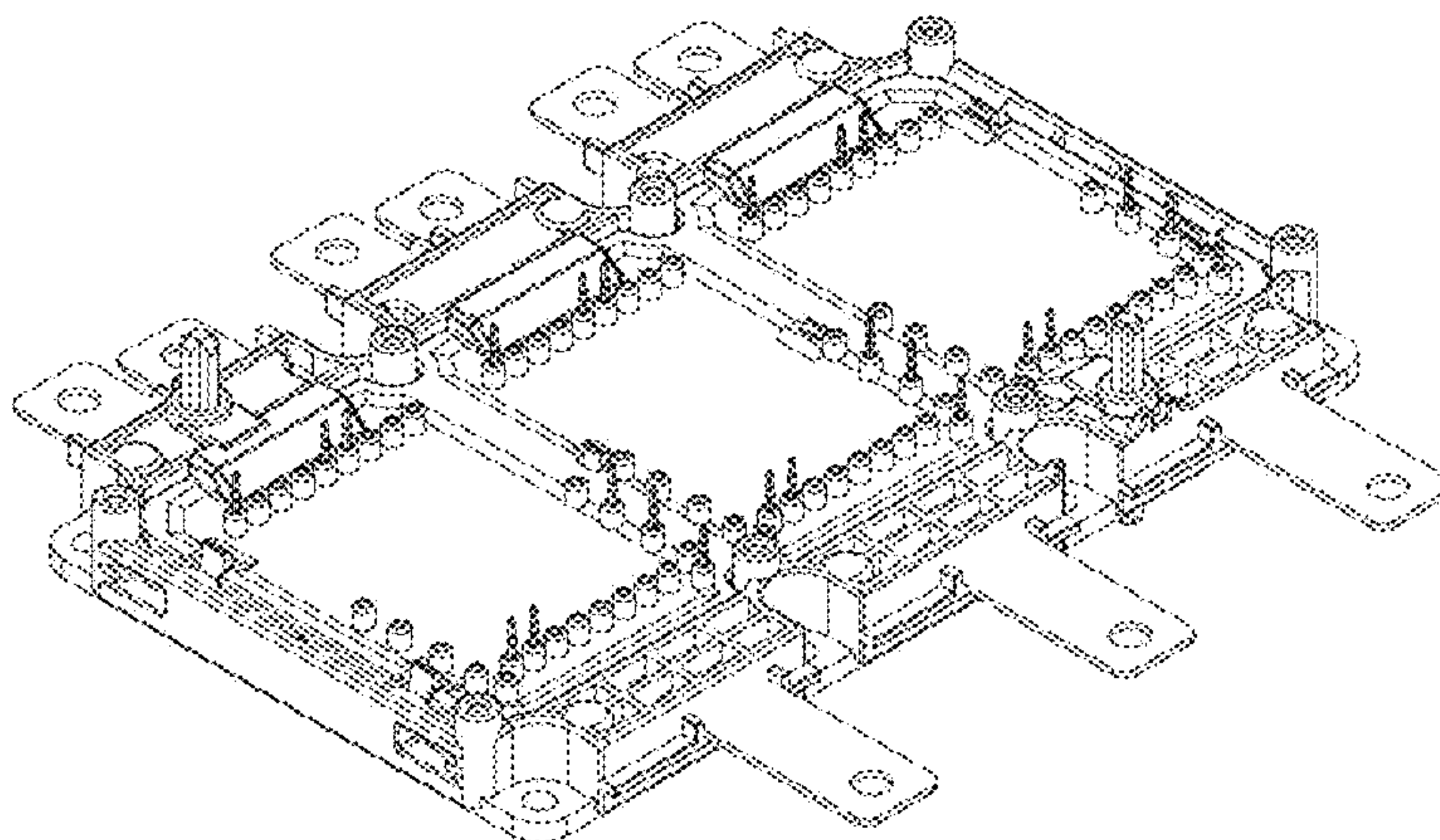
(57) **CLAIM**

The ornamental design for a power semiconductor module,
as shown and described.

DESCRIPTION

FIG. 1 is a bottom plan view of a power semiconductor
module showing our new design;
FIG. 2 is a top plan view thereof;
FIG. 3 is a side elevational view thereof;
FIG. 4 is another side elevational view thereof; and,
FIG. 5 is a top, side perspective view thereof.
All surfaces not shown form no part of the claimed design.

1 Claim, 5 Drawing Sheets



(56)

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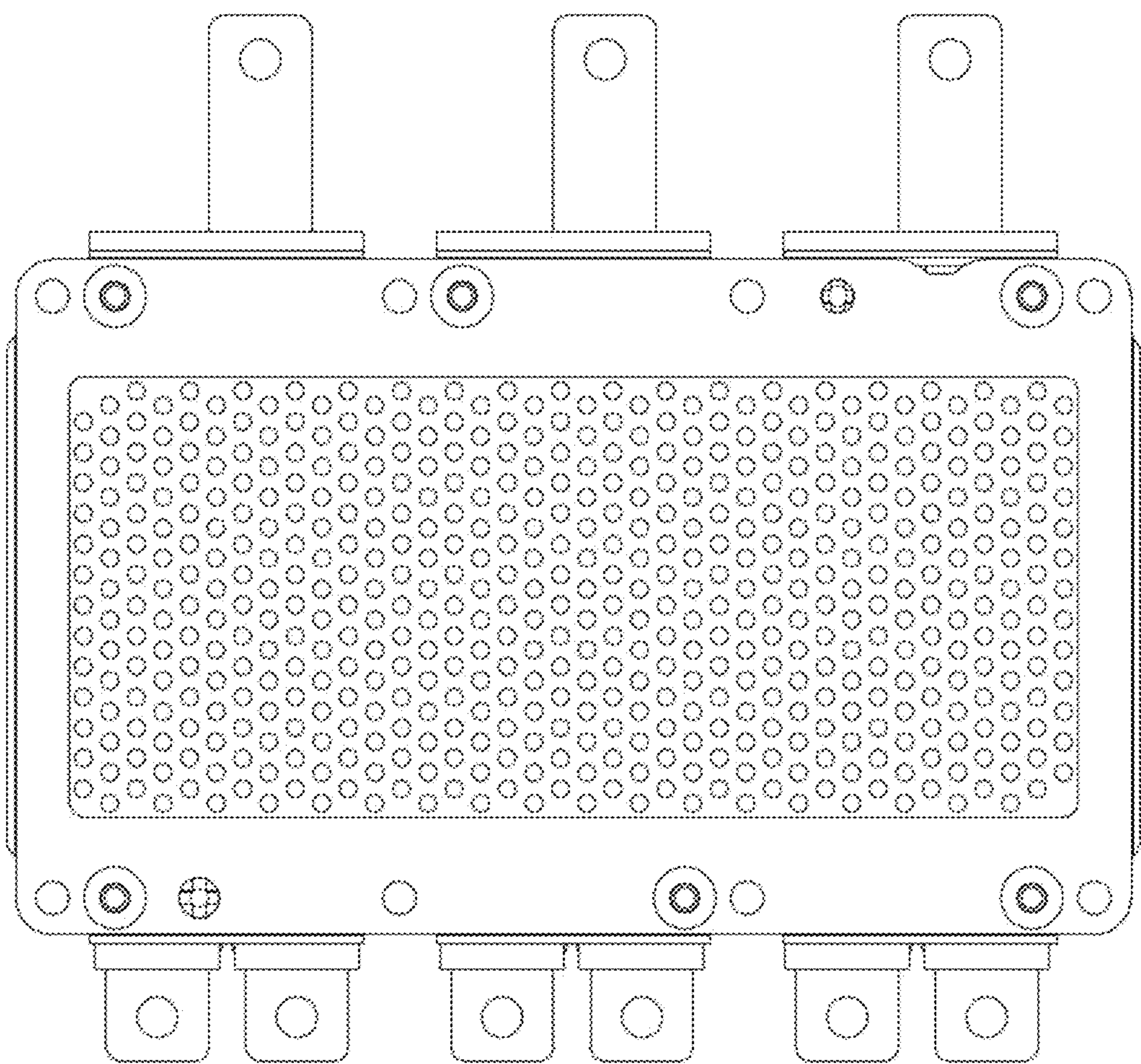


Figure 1

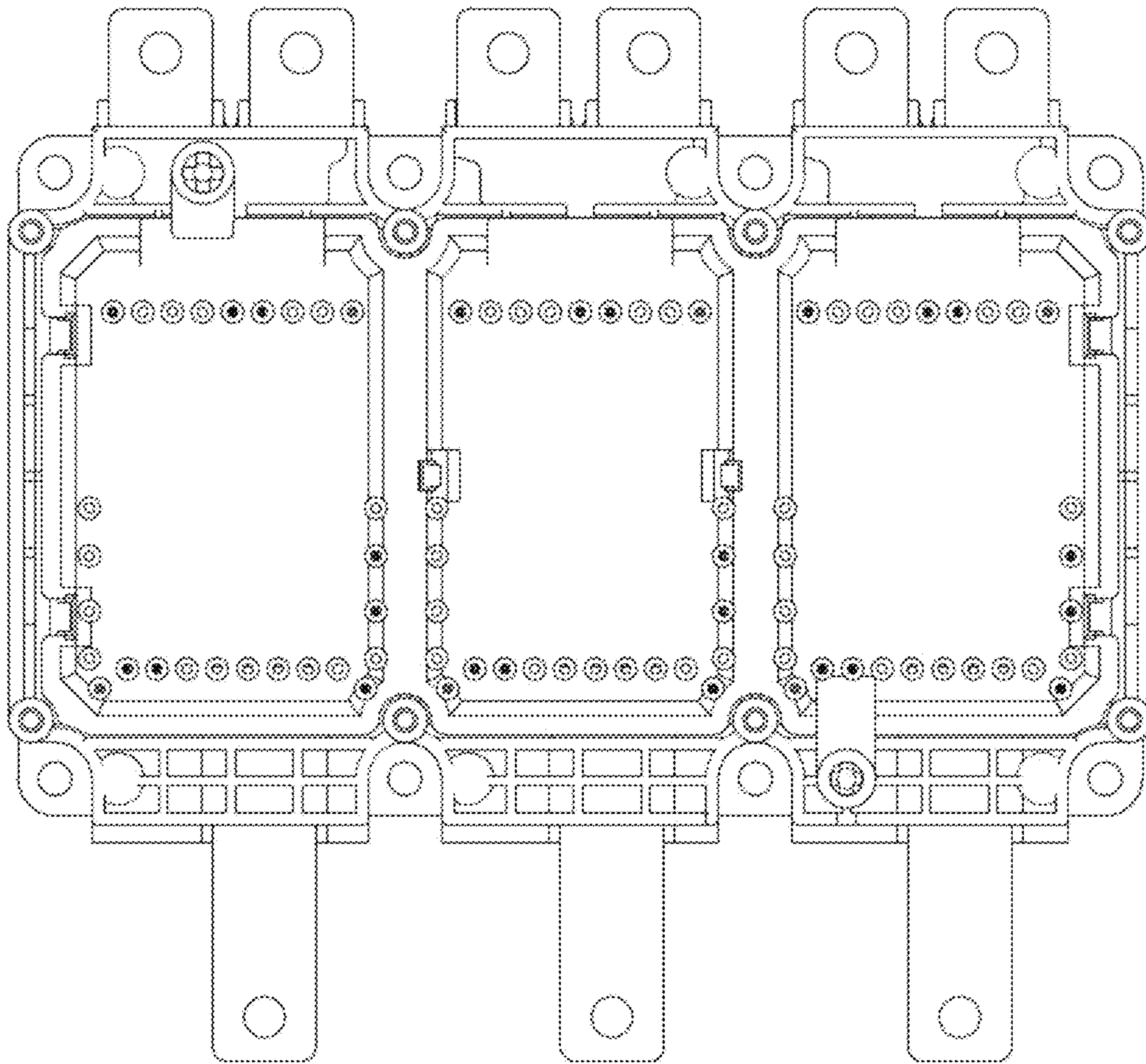


Figure 2

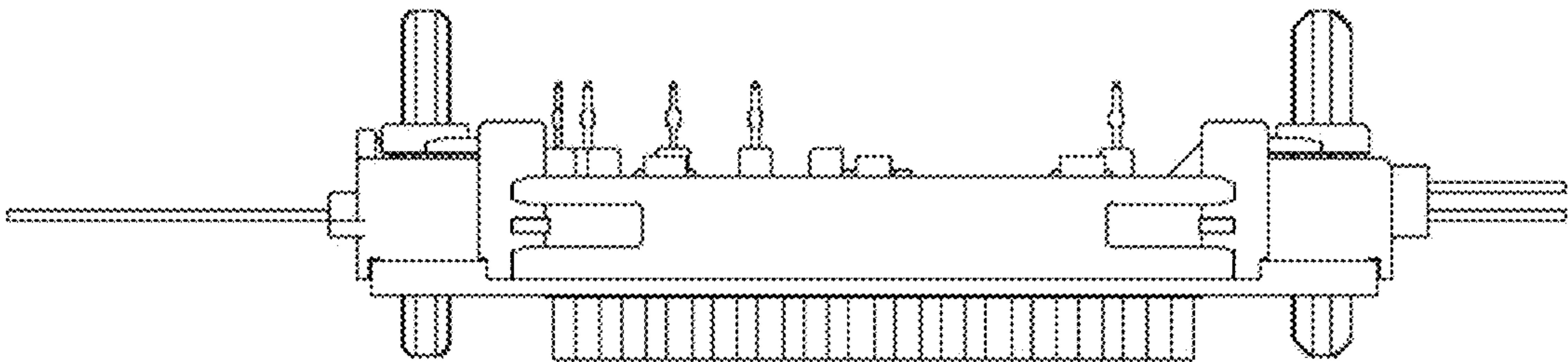


Figure 3

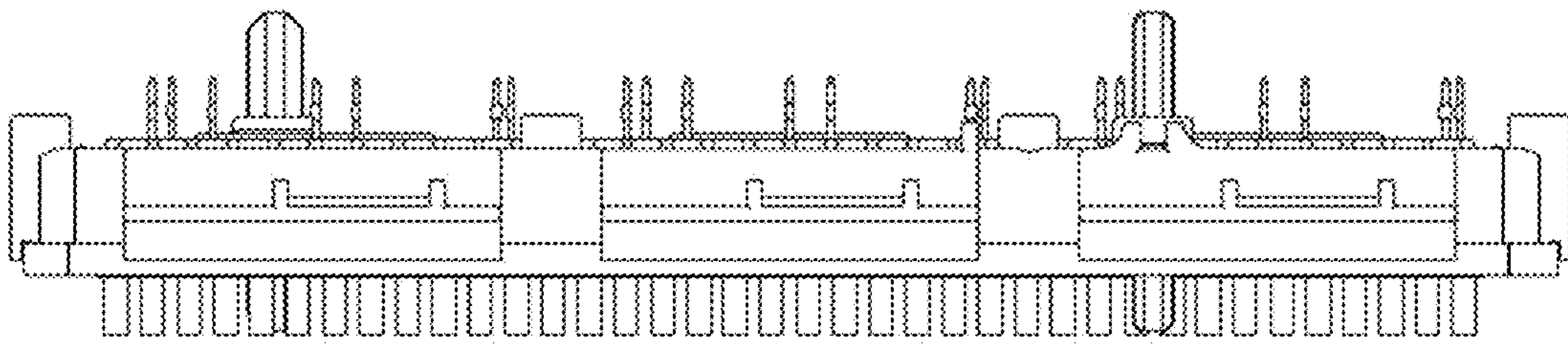


Figure 4

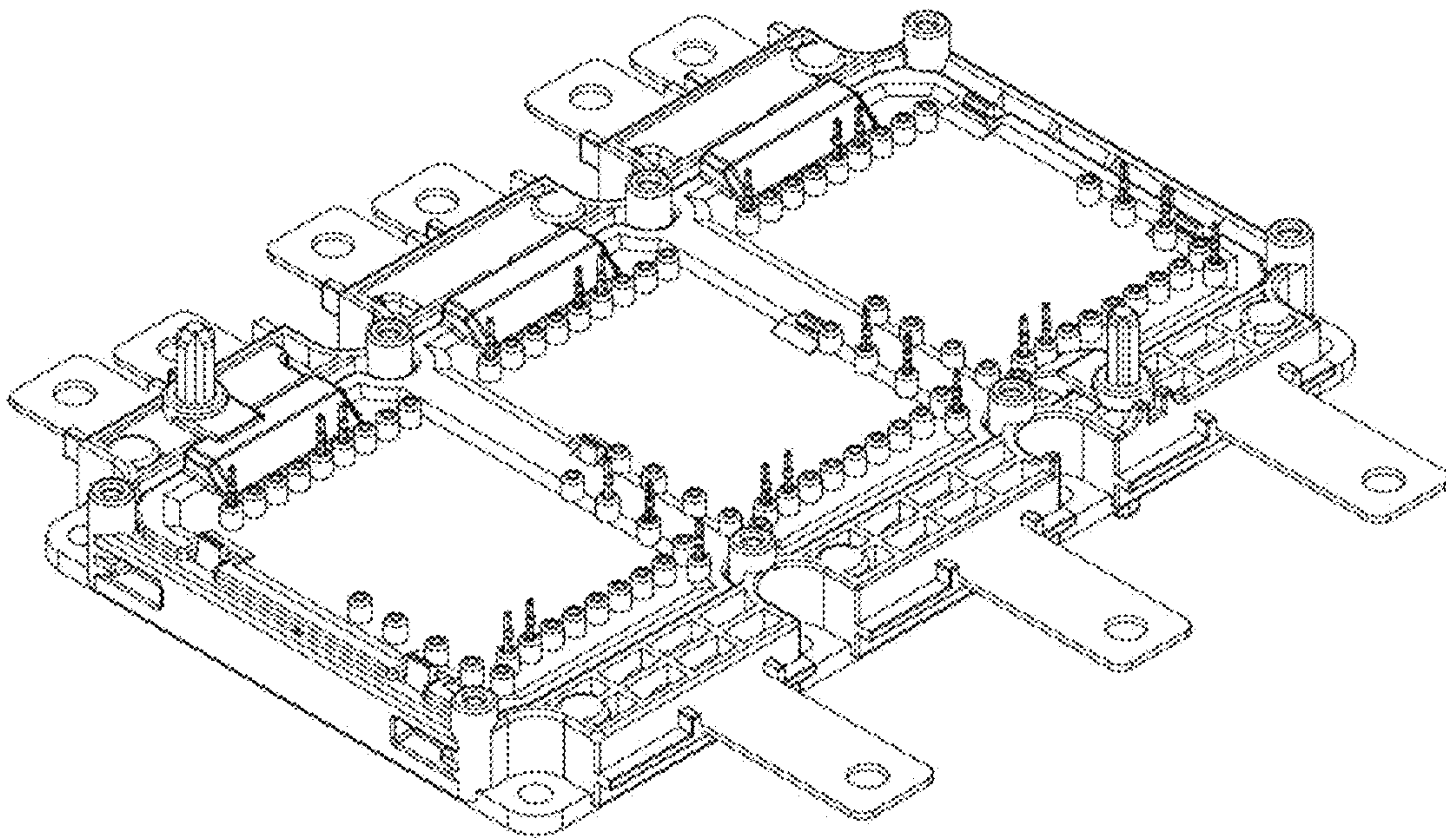


Figure 5